Model 850
Flip Chip
Placement System

The Model 850 is a versatile, semi-automatic placement system ideal for flip chips, chip scale devices and bare die. Intended for low volume production and development projects requiring accuracies of +/- 12 microns.



Features

- +/- 12 micron placement accuracy
- Color video system with motorized zoom lens
- LED Ring Lights
- Micrometer adjusted Stage
- Bond load 30-200g standard (2kg optional)
- Sliding table with 5" x 12" travel

Options:

- Manual or motorized flux station
- Hot gas spot heating (Model 430)
- Die tray pedestal
- Heated workstage to 350° C
- Vacuum workstage

Facilities

- Line voltage: 115 VAC, 60 Hz, 8 AMP or 230V, 50Hz, 4 AMP
- Vacuum minimum: 25"Hg; ¼" OD tubing
- Compressed air: regulated to 50 PSI, filtered to 50 um, 1/4" OD tubing

Dimensions

- Weight: Machine 185 Lb., Shipping 225 lb. (basic, weight varies with added options)
- Recommended bench top allowance: 60"wide x 30"deep; Height allowance 30"

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